



UPDATE CHANGE NOTIFICATION

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05-Mar-2009

SUBJECT: ON Semiconductor Update Notification #16226

TITLE: Additional SC74 Products to the Leshan, China Manufacturing Site

PROPOSED FIRST SHIP DATE: 03-June-2009

AFFECTED CHANGE CATEGORY(S): Assembly/Final Test

AFFECTED PRODUCT DIVISION(S): PowerFET Business Unit

ADDITIONAL RELIABILITY DATA:

NTGD1100LT1G

Test: Temperature Cycling (TC-PC)

Conditions: Ta=-65'C/150'C, Air-to-Air, Dwell >=10-min, 1000-cy, 3-Lots

Results: 0/240

Test: Autoclave Test (AC-PC)

Conditions: Ta=121'C, P=15psi, RH=100%, Duration: 96-Hrs, 3-Lots

Results: 0/240

Test: Highly Accelerated Stress Test (HAST)

Conditions: Ta=130'C, RH=85%, Duration: 96-Hrs, 3-Lots

Results: 0/240

Test: SAT (pre and post MSL1 Testing)

Results: 0/15

SAMPLES: Contact your local ON Semiconductor Sales Office or Jennie Shen

<Jennie.Shen@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Office or Jennie Shen

<Jennie.Shen@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**Update Notification #16226****DESCRIPTION AND PURPOSE:**

An addendum to Final Product/Process Change Notification #15573:

ON Semiconductor is notifying customers that the NTGD1100LT1 and NTGD1100LT1G will be added to the list of SC74 (Tsop6 Dual) Products currently assembled and electrically tested at both ON Semiconductor manufacturing facilities located in Seremban, Malaysia and Leshan, China. Currently, the NTGD1100LT1 and NTGD1100LT1G are only built and tested from their Seremban manufacturing facility.

The mold compound, die attach, and lead frame materials used for the this Package will not be changed. Reliability Qualification and full electrical characterization over temperature have been performed showing no difference regardless of where the product is built.

AFFECTED DEVICE LIST

NTGD1100LT1
NTGD1100LT1G